

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage V_{GS(th)} <1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- ESD Protected Gate to 2.5kV HBM
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. • UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 7
- Ordering Information: See Page 7
- Weight: 0.006 grams (approximate)



ESD PROTECTED TO 2.5kV HBM



SOT-563



TOP VIEW

Internal Schematic

Maximum Ratings N-CHANNEL - Q₁ @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	±6	V
Drain Current (Note 1) $T_A = 2$ $T_A = 8$	25°C I _D	870 630	mA

Maximum Ratings P-CHANNEL – Q_2 @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Drain Source Voltage		V _{DSS}	-20	V
Gate-Source Voltage		V _{GSS}	±6	V
IDrain Current (Note 1)	Γ _A = 25°C Γ _A = 85°C	I _D	-640 -460	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	530	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ ext{ heta}JA}$	235	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes: 1. Device mounted on FR-4 PCB.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

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Electrical Characteristics N-CHANNEL – Q_1 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 4)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	± 1.0	μΑ	$V_{GS} = \pm 4.5 V$, $V_{DS} = 0 V$	
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(th)}	0.5	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS (ON)}		0.3 0.4 0.5	0.4 0.5 0.7	Ω	$V_{GS} = 4.5V, I_D = 600mA$ $V_{GS} = 2.5V, I_D = 500mA$ $V_{GS} = 1.8V, I_D = 350mA$	
Forward Transfer Admittance	Y _{fs}	_	1.4	_	S	$V_{DS} = 10V, I_{D} = 400mA$	
Diode Forward Voltage (Note 4)	V _{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}	_	60.67	_	pF		
Output Capacitance	C _{oss}	_	9.68	—	pF	V _{DS} = 16V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	5.37	—	pF		
Total Gate Charge	Q_g	_	736.6	_			
Gate-Source Charge	Q _{gs}	_	93.6	_	рС	$V_{GS} = 4.5V, V_{DS} = 10V,$ In = 250mA	
Gate-Drain Charge	Q _{gd}		116.6			ID = 230 IIIA	
Turn-On Delay Time	t _{d(on)}		5.1	—			
Turn-On Rise Time	tr		7.4	—	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 47\Omega, R_{G} = 10\Omega,$	
Turn-Off Delay Time	t _{d(off)}		26.7	—	115	$R_L = 4752, R_G = 1052,$ $I_D = 200 \text{mA}$	
Turn-Off Fall Time	t _f	_	12.3	_		ID = 200IIIA	

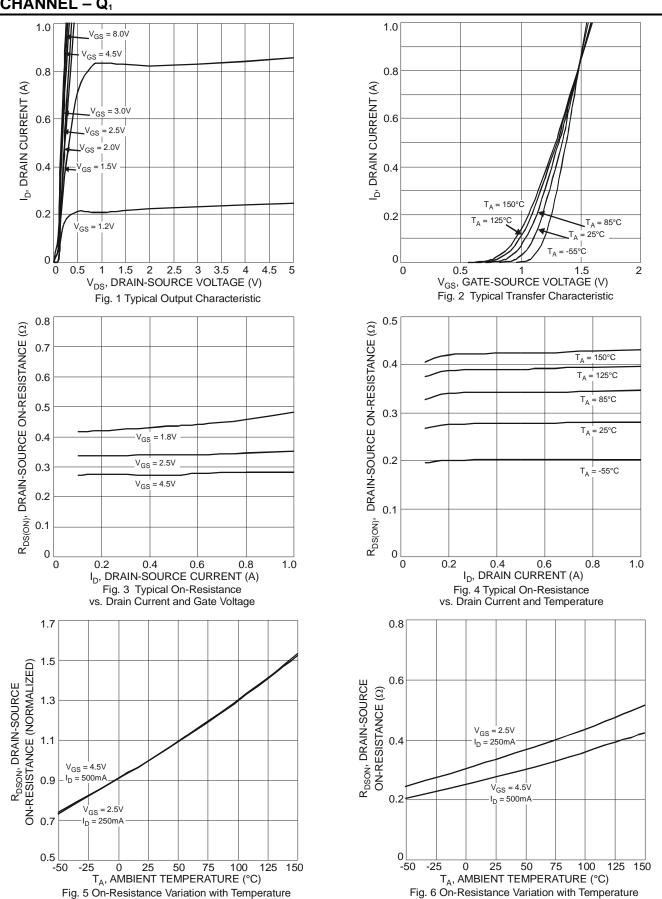
Electrical Characteristics P-CHANNEL – Q_2 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 4)	Symbol	WIIII	тур	WIAA	Unit	Test condition	
Drain-Source Breakdown Voltage	BV _{DSS}	-20			V	$V_{GS} = 0V, I_D = -250 \mu A$	
Zero Gate Voltage Drain Current		-20		-100	nA	$V_{\rm DS} = -20V, V_{\rm GS} = 0V$	
Gate-Source Leakage	I _{DSS}			± 2.0	μA	$V_{DS} = -20V, V_{DS} = 0V$ $V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 4)	IGSS			± 2.0	μΑ	$v_{GS} = \pm 4.5 v, v_{DS} = 0 v$	
Gate Threshold Voltage	V _{GS(th)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	R _{DS} (ON)		0.5 0.7 1.0	0.7 0.9 1.3	Ω	$V_{GS} = -4.5V$, $I_D = -2.00\mu A$ $V_{GS} = -4.5V$, $I_D = -430m A$ $V_{GS} = -2.5V$, $I_D = -300m A$ $V_{GS} = -1.8V$, $I_D = -150m A$	
Forward Transfer Admittance	Y _{fs}	_	-0.9	_	S	$V_{DS} = 10V, I_D = -250mA$	
Diode Forward Voltage (Note 4)	V _{SD}	_	-0.8	-1.2	V	$V_{GS} = 0V, I_S = -150mA$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}		59.76	—	pF		
Output Capacitance	C _{oss}		12.07		pF	V _{DS} = -16V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}		6.36		pF		
Total Gate Charge	Qg		622.4	_			
Gate-Source Charge	Q _{gs}		100.3	_	рС	$V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -250mA$	
Gate-Drain Charge	Q _{gd}	_	132.2	_		$I_D = -250 \text{mA}$	
Turn-On Delay Time	t _{d(on)}		5.1				
Turn-On Rise Time	tr		8.1	_	ns	$V_{DD} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t _{d(off)}		28.4	—	115	$R_{L} = 47\Omega, R_{G} = 10\Omega,$	
Turn-Off Fall Time	t _f	_	20.7	_	I _D = -200mA		

Notes: 4. Short duration pulse test used to minimize self-heating effect.

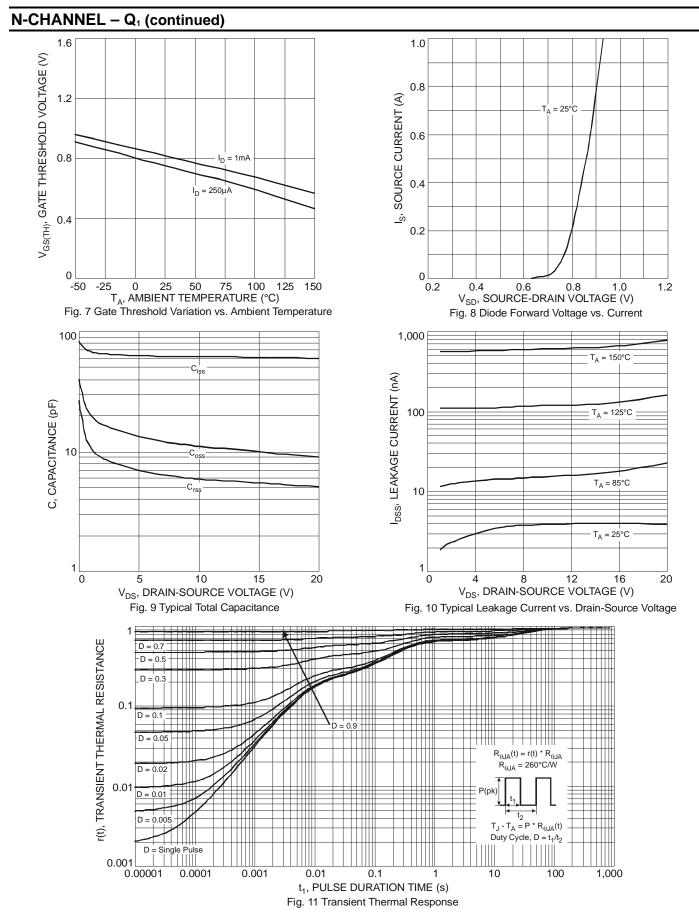


N-CHANNEL – Q₁



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DMG1016V

T_A = 85°C = 25°C -55°C

2.0

2.5

 $T_{A} = 150^{\circ}C$

T_A = 125°C

 $T_A = 85^{\circ}C$

 $T_A = 25^{\circ}C$

 $T_A = -55^{\circ}C$

0.8

0.6

50

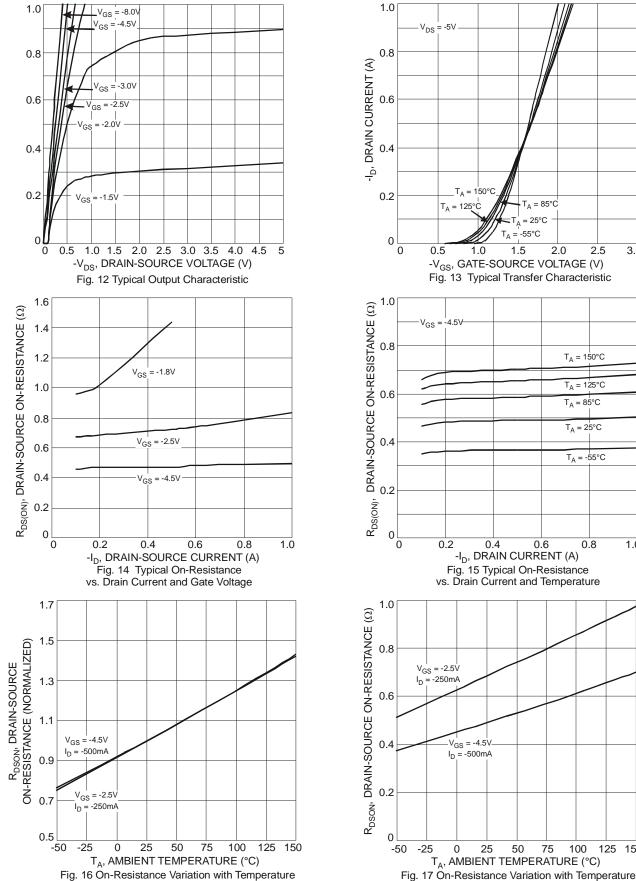
75

3.0

1.0

1.5



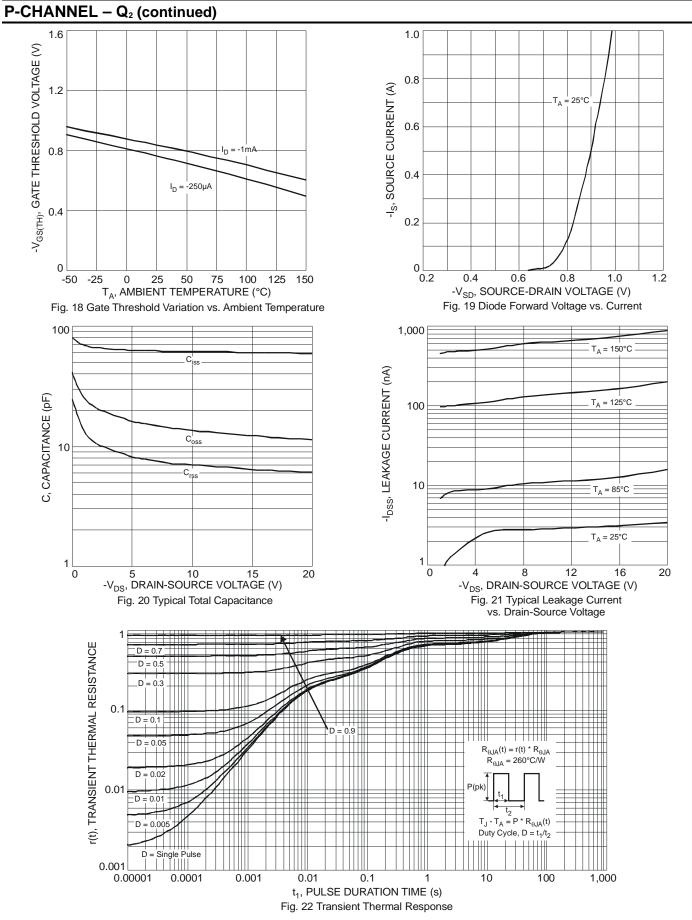


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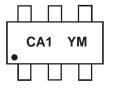


Ordering Information (Note 5)

Part Number	Case	Packaging
DMG1016V-7	SOT-563	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information

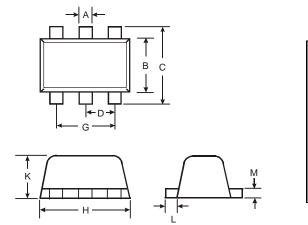


CA1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

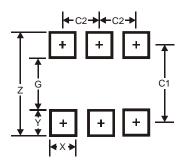
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Y		Ζ	А		В		С
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Package Outline Dimensions



SOT-563						
Dim	Min	Max	Тур			
Α	0.15	0.30	0.20			
В	1.10	1.25	1.20			
С	1.55	1.70	1.60			
D	-	-	0.50			
G	0.90	1.10	1.00			
Н	1.50	1.70	1.60			
Κ	0.55	0.60	0.60			
L	0.10	0.30	0.20			
М	0.10	0.18	0.11			
All	Dimens	sions in	mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5

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